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FCP16N60 / FCPF16N60 N-Channel SuperFET[®] MOSFET **600 V, 16 A, 260 m**Ω

Features

- 650V @ T_J = 150°C
- Typ. R_{DS(on)} = 220 mΩ
- Ultra Low Gate Charge (Typ. Q_g = 55 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 110 pF)
- · 100% Avalanche Tested

Applications

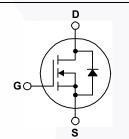
- Solar Inverter
- · AC-DC Power Supply

Description

SuperFET[®] MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.







Absolute Maximum Ratings

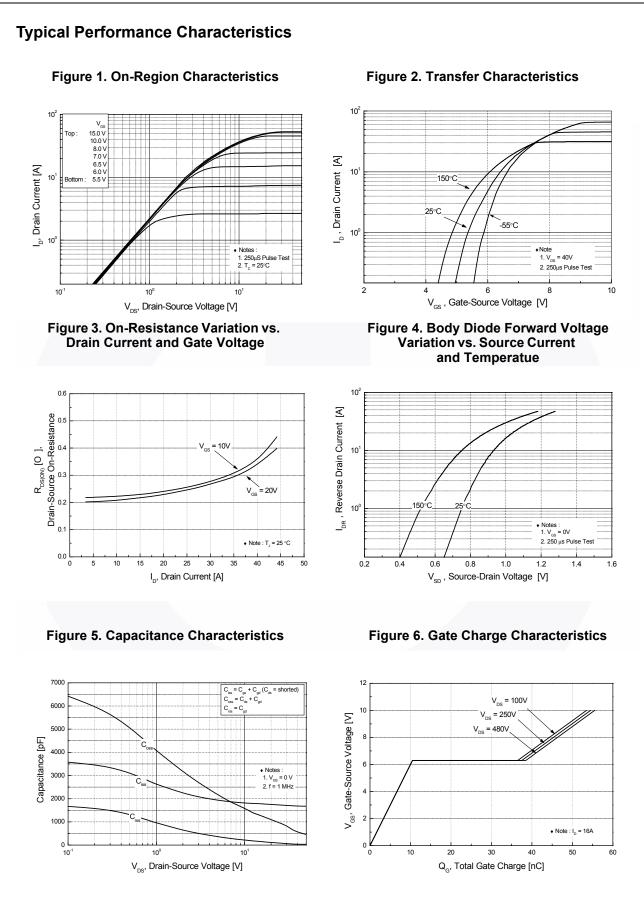
Symbol		Parameter		FCP16N60	FCPF16N60	Unit
V _{DSS}	Drain-Source Voltage			6	V	
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		16 10.1	16* 10.1*	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	48	48*	А
V _{GSS}	Gate-Source Voltage			±	V	
E _{AS}	Single Pulsed Avalanche Energy			4	mJ	
I _{AR}	Avalanche Current		(Note 1)	16		А
E _{AR}	Repetitive Avalanche Energy		(Note 1)	20.8		mJ
dv/dt	Peak Diode Recov	very dv/dt	(Note 3)	4.5		V/ns
P _D	Power Dissipation	(T _C = 25°C) - Derate Above 25°C		167 1.33	37.9 0.3	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range			-55 to	°C	
Τ _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			3	°C	

*Drain current limited by maximum junction temperature.

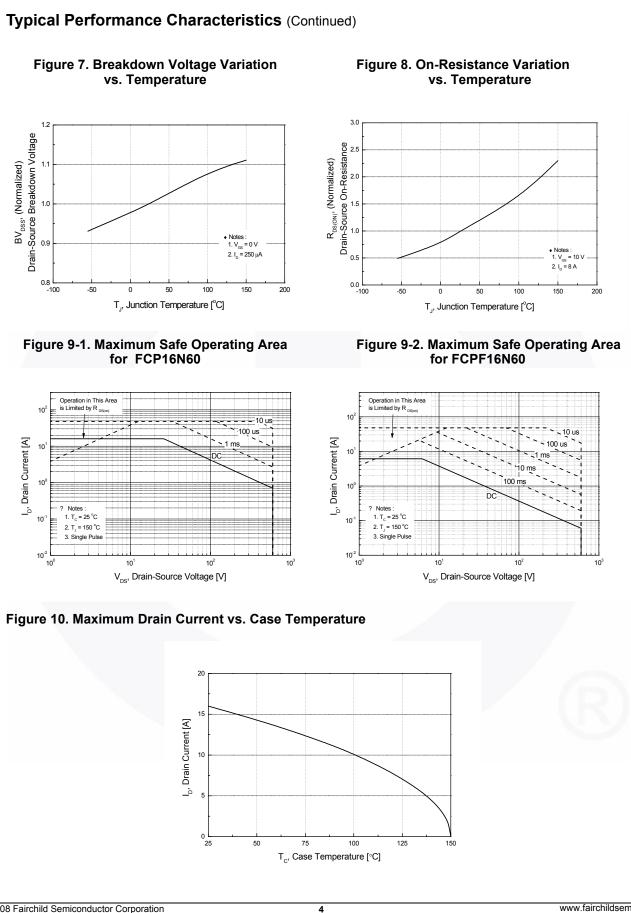
Thermal Characteristics

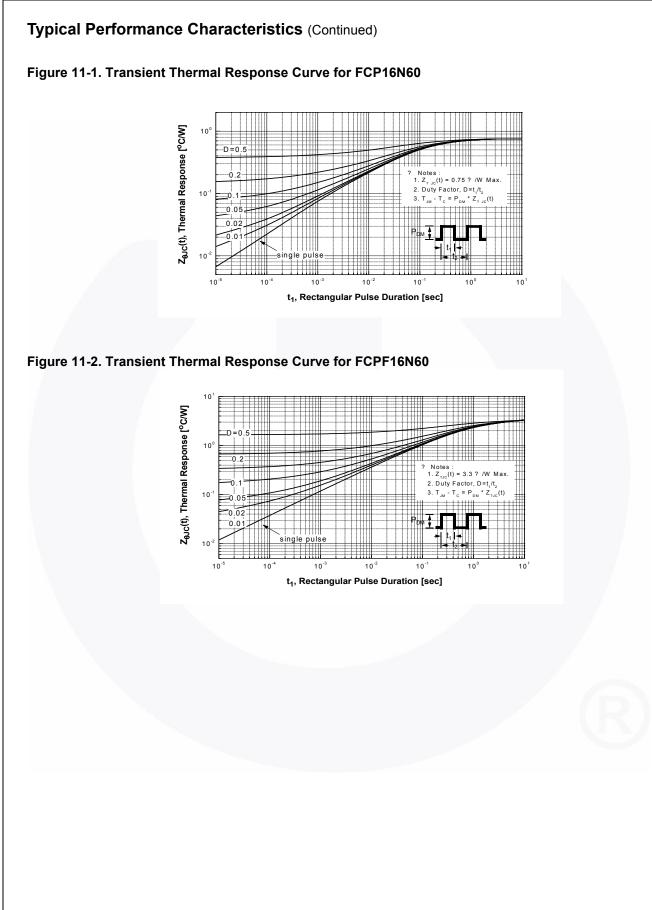
Symbol	Parameter	FCP16N60	FCPF16N60	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.75	3.3	°C/W
R_{\thetaJA}	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

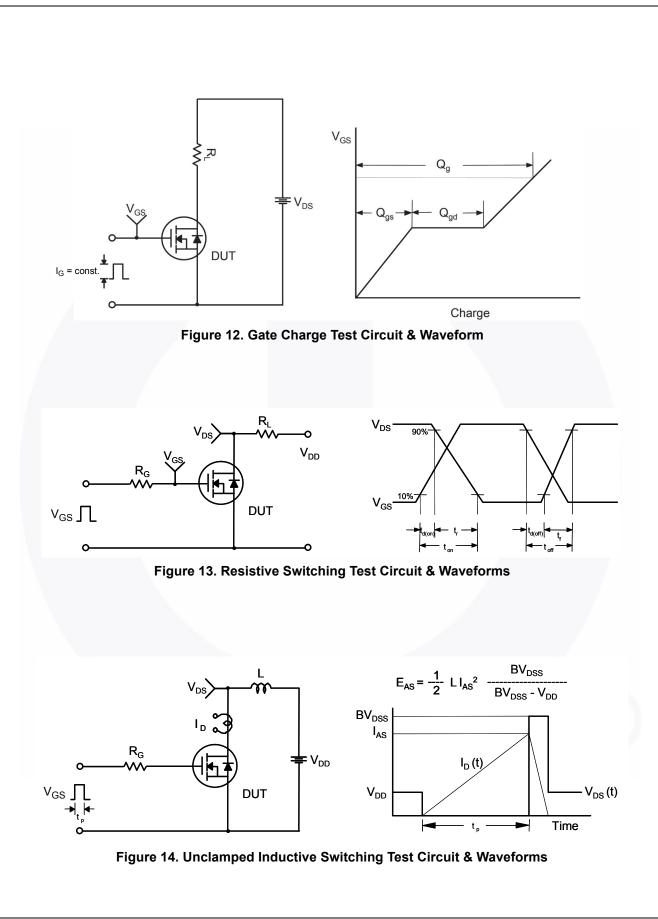
60 N60	FCP16N60	TO 0					e Width		
160		TO-22	20	Tube	N/A		N/A	50 u	units
	FCPF16N60 FCPF16N60 TC			20F Tube N/A			N/A	50 units	
Chara	cteristics T _c = 2	25°C unles	ss oth	erwise noted.					
							Τνρ.	Max.	Unit
teristics									
			$I_{D} = 250 \mu\text{A}, V_{GS} = 0 \text{V}, T_{1} = 25^{\circ}\text{C}$			600	-	-	V
		•	$I_D = 250 \ \mu\text{A}, \ V_{GS} = 0 \ V, \ T_J = 150^{\circ}\text{C}$			-	650	-	V
Breakdown Voltage Temperature Coefficient		3	I_D = 250 µA, Referenced to 25°C			-	0.6	-	V/ºC
Drain-Source Avalanche Breakdown Voltage			V _G	V _{GS} = 0 V, I _D = 16 A			700	-	v
Zoro Cato Voltago Drain Current				V _{DS} = 600 V, V _{GS} = 0 V		-	-	1	μA
Zero Gale voltage Drain Current			V _{DS} = 480 V, T _C = 125 ^o C			-	-	10	
Gate to Body Leakage Current			VG	_{is} = ±30 V, V _{DS} = 0 V		-	-	±100	nA
teristics									
Gate Threshold Voltage			V _{GS} = V _{DS} , I _D = 250 μA			3.0	-	5.0	V
Static Drain to Source On Resistance						-	0.55	0.26	Ω
Forward Transconductance			$V_{DS} = 40 \text{ V}, \text{ I}_{D} = 8 \text{ A}$			-	11.5	-	S
haracte	ristics								
1					-	1730	2250	pF	
					-	960	1150	pF	
			f =	f = 1 MHz		-		-	pF
			V _{DS} = 480 V, V _{GS} = 0 V, f = 1 MHz			-			pF
						-	110	-	pF
					-	55	70	nC	
	Gate to Source Gate Charge				-			nC	
			(Note 4)			-		-	nC
	Ū		f = 1 MHz			-	1.7	-	Ω
Characte	eristics						I	I	
1							42	85	ns
Turn-On Rise Time			$V_{\rm res} = 300 \text{V}$ L = 16 A					ns	
						_			ns
			(Note 4)			-			ns
1									
					_		16	A	
Maximum							-	48	А
						-	-	1.4	V
Reverse I	Recovery Time		$V_{GS} = 0 V, I_{SD} = 16 A,$ $dI_F/dt = 100 A/\mu s$		-	435	-	ns	
Reverse I	Recovery Charge				-	7.0	-	μC	
	Drain to S Breakdow Coefficien Drain-So Voltage Zero Gat Gate to E teristics Gate Thr Static Dra Forward haracter Input Cap Output C Effective Total Gat Gate to E Equivalen Character Turn-On Turn-On Turn-Off Turn-Off Turn-Off Turn-Off Turn-Off Ce Diode Maximum Drain to S Reverse	Breakdown Voltage Temperature Coefficient Drain-Source Avalanche Breakd Voltage Zero Gate Voltage Drain Current Gate to Body Leakage Current teristics Gate Threshold Voltage Static Drain to Source On Resist Forward Transconductance haracteristics Input Capacitance Output Capacitance Output Capacitance Reverse Transfer Capacitance Output Capacitance Effective Output Capacitance Total Gate Charge at 10V Gate to Source Gate Charge Gate to Drain "Miller" Charge Equivalent Series Resistance Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Fall Time Ce Diode Characteristics Maximum Continuous Drain to S Maximum Pulsed Drain to Source	teristics Drain to Source Breakdown Voltage Breakdown Voltage 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$V_{GS} = 10 \ V, \ I_D = 8 \ A$ Forward Transconductance $V_{DS} = 400 \ V, \ I_D = 8 \ A$ haracteristicsInput CapacitanceOutput Capacitance $V_{DS} = 25 \ V, \ V_{GS} = 0 \ V, \ f = 1 \ MHz$ Output Capacitance $V_{DS} = 480 \ V, \ V_{GS} = 0 \ V, \ f = 1 \ MHz$ Output Capacitance $V_{DS} = 0 \ V \ to 400 \ V, \ V_{GS} = 0 \ V, \ GS = 10 \ V$ Gate to Source Gate Charge $V_{DS} = 480 \ V, \ I_D = 16 \ A, \ V_{GS} = 10 \ V$ Gate to Drain "Miller" Charge $V_{GS} = 10 \ V, \ GS = 10 \ V$ Equivalent Series Resistancef = 1 \ MHzCharacteristics $V_{DD} = 300 \ V, \ I_D = 16 \ A, \ V_{GS} = 10 \ V, \ GS = 10 \ V, \ R_G = 25 \ \Omega$ Turn-Off Delay Time $V_{CS} = 0 \ V, \ R_G = 25 \ \Omega$ Turn-Off Fall Time $V_{GS} = 0 \ V, \ R_G = 25 \ \Omega$ Maximum Continuous Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentDrain to Source Diode Forward VoltageV _{GS} = 0 V, \ I_SD = 16 \ A, \ Reverse 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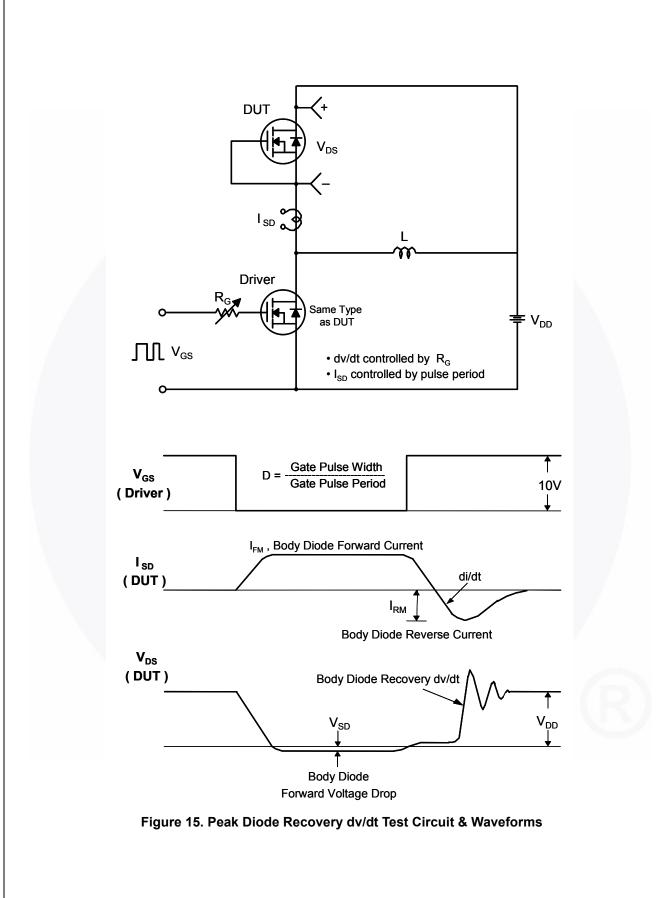


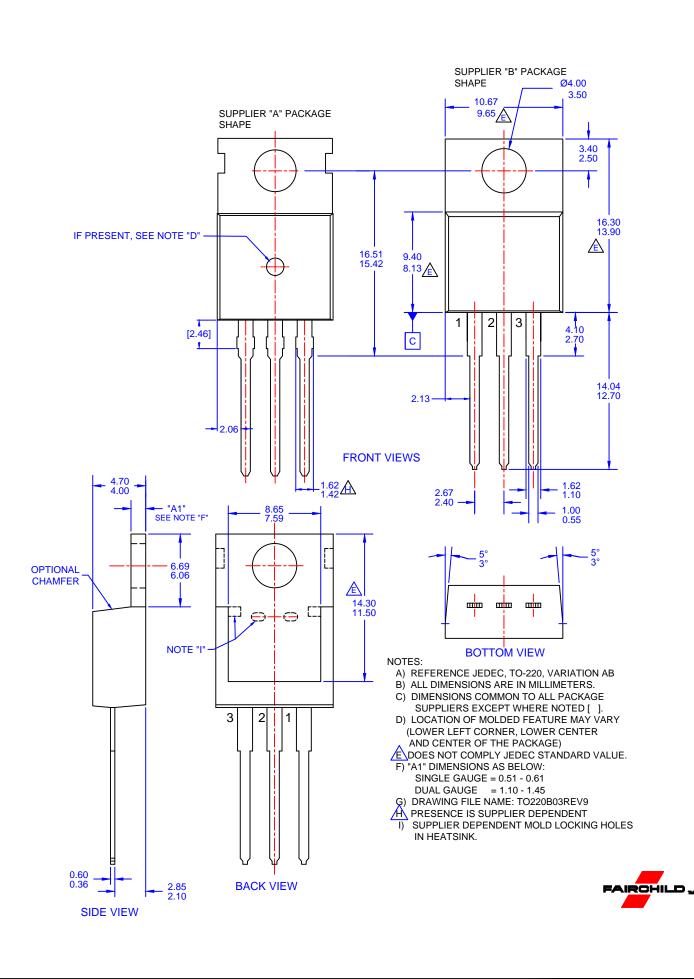




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FCP16N60 / FCPF16N60 — N-Channel SuperFET[®] MOSFET







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